



40V 10A GATE DRIVER IN SOT26

Description

The ZXGD3006E6Q is a 40V Gate Driver for switching IGBTs and SiC MOSFETs. It can transfer up to 10A peak source/sink current into the gate for effective charging and discharging of a large capacitive load.

The ZXGD3006E6Q can drive typically 4A into the low gate impedance of an IGBT, with just 1mA input from a controller. Also, the turn-on and turn-off switching behavior of the IGBT can be individually tailored to suit an application. In particular, by defining the switching characteristics appropriately, EMI and cross conduction can be reduced.

Applications

Gate driving IGBTs and SiC MOSFETs in:

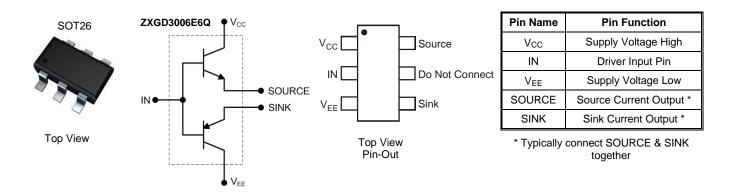
- DC-DC Converters in Electric Cars
- Automotive Active Suspension Systems
- Solar Inverters
- Power Supplies
- Plasma Display Panel Power Modules

Features

- High-Gain Buffer with Typically 4A Output from 1mA Input
- 40V Supply for +20V to -18V gate driving to prevent dV/dt induced false triggering
- Emitter-Follower that is Rugged to Latch-Up / Shoot-Through Issues, and Delivers <10ns Propagation Delay Time
- Optimized Pin-Out to Simplify PCB Layout and Reduce
 Parasitic Trace Inductances
- Near-Zero Quiescent Supply Current
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability
- PPAP Capable (Note 4)

Mechanical Data

- Case: SOT26
- Case Material: Molded Plastic. "Green" Molding Compound. UL Flammability Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Plated Leads. Solderable per MIL-STD-202, Method 208 ⁽²³⁾
- Weight: 0.018 grams (Approximate)



Ordering Information (Note 5)

Product	Compliance	Marking	Reel Size (inches)	Tape Width (mm)	Quantity per Reel
ZXGD3006E6QTA	Automotive	3006	7	8	3,000

1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.

2. See http://www.diodes.com/quality/lead_free/ for more information about Diodes Incorporated's definitions of Halogen and Antimony free, "Green" and Lead-Free.

3. Halogen and Antimony free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4. Automotive products are AEC-Q101 qualified and are PPAP capable. Refer to https://www.diodes.com/quality/.

5. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Notes:



Marking Information

SOT26

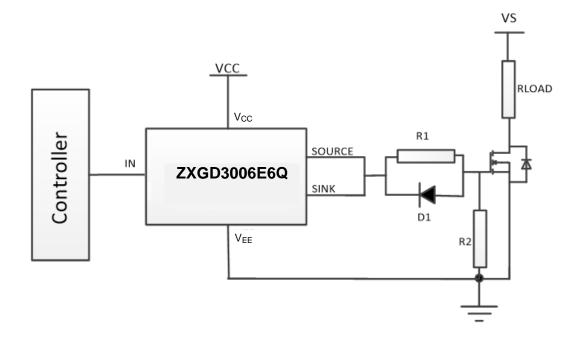


 $\begin{array}{l} 3006 = \mbox{Product Type Marking Code} \\ \mbox{YM} = \mbox{Date Code Marking} \\ \mbox{Y or } \overline{Y} = \mbox{Year (ex: F} = 2018) \\ \mbox{M or } \overline{M} = \mbox{Month (ex: 9} = \mbox{September)} \end{array}$

Date Code Key

Year	2018	2	2019	2020	2021	2022	2022	2023	3 20	24	2025	2026	2027
Code	F		G	Н		J	K	L	N	N	Ν	0	Р
Month	n	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code		1	2	3	4	5	6	7	8	9	0	N	D

Typical Application Circuit



R1, D1 combination can be used for variable turn on and turn off times.



Absolute Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Supply Voltage, with Respect to V _{EE}	V _{CC}	40	V
Input Voltage, with Respect to V _{EE}	V _{IN}	40	V
Output Difference Voltage (Source – Sink)	$\Delta V_{(source-sink)}$	±7	V
Peak Pulsed Output Current (Source – Sink)	IOM	±10	A
Peak Pulsed Input Current	l _{IN}	±100	mA

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Power Dissipation (Notes 6 & 7)	D	1.1	W
Linear Derating Factor	PD	8.8	mW/°C
Thermal Resistance, Junction to Ambient (Notes 6 & 7)	R _{0JA}	113	°C/W
Thermal Resistance, Junction to Lead (Note 8)	R _{θJL}	105	C/VV
Operating and Storage Temperature Range	T _{J,} T _{STG}	-55 to +150	°C

ESD Ratings (Note 9)

Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	1,500	V	1C
Electrostatic Discharge – Charged Device Model	ESD CDM	1,000	V	IV

Notes: 6. For a device mounted on 25mm x 25mm 1oz copper that is on a single-sided 1.6mm FR-4 PCB; device is measured under still air conditions whilst operating in a steady-state. The heatsink is split in half with the pin 1 (V_{CC}) and pin 3 (V_{EE}) connected separately to each half.

7. For device with two active die running at equal power.

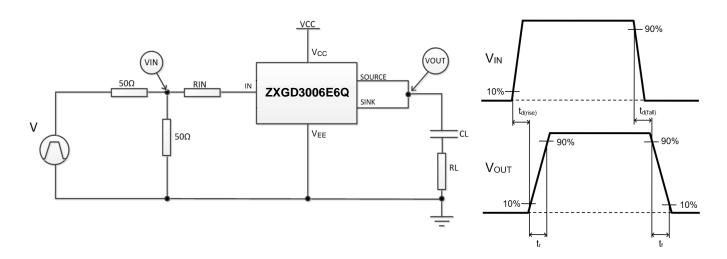
8. Thermal resistance from junction to solder-point at the end of each lead on pin 1 (V_{CC}) and pin 3 (V_{EE}). 9. Refer to JEDEC specification JESD22-A114 and JESD22-C101.



Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

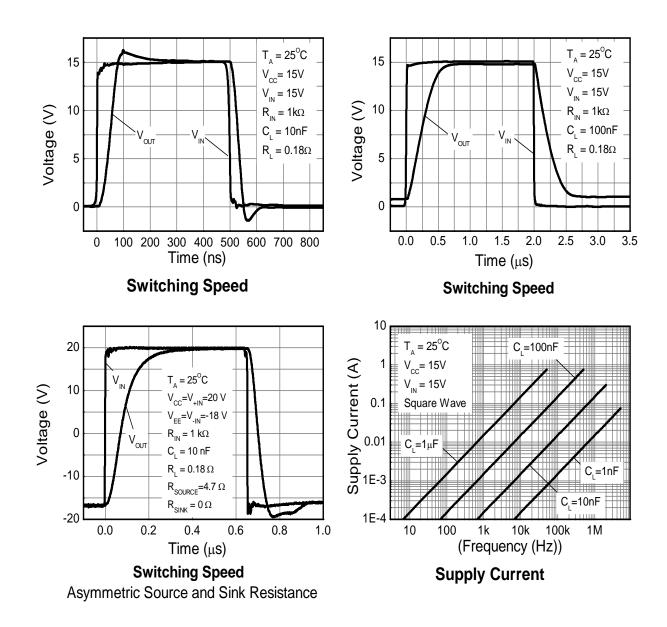
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Output Voltage, High	V _{OUT(hi)}	V _{CC} - 1.0	V _{CC} - 0.8	_	V	$V_{IN} = V_{CC}$
Output Voltage, Low	V _{OUT(low)}	_	V _{EE} + 0.12	V _{EE} + 0.3	v	$\frac{V_{IN} - V_{CC}}{V_{IN} = V_{EE}} C_L = 1 nF$
Supply Breakdown Voltage		40		—	V	$I_Q = 100 \mu A, V_{IN} = V_{CC}$
Supply Breakdown voltage	BV _{CC}	40		—		$I_Q = 100 \mu A, V_{IN} = V_{EE} = 0V$
Quiescent Supply Current		—		50	nA	$V_{CC} = 30V, V_{IN} = V_{CC}$
Quiescent Supply Current	Ι _Q	—		50	ΠA	$V_{CC} = 30V, V_{IN} = V_{EE} = 0V$
Peak Pulsed Source Current	I _{(source)M}	_	4.0	_	٨	$V_{CC} = 5V$, $I_{IN} = 1mA$, $V_{OUT} = 0V$
Peak Pulsed Sink Current	I _{(sink)M}	—	3.8	—	A	$V_{CC} = 5V$, $I_{IN} = -1mA$, $V_{OUT} = 5V$
Source Current with Varying Input Resistances	ISOURCE	_	6.4 5.5 3.9 2.2 0.44	_	A	$ \begin{array}{l} R_{IN} = 200\Omega \\ R_{IN} = 1k\Omega \\ V_{IN} = 10k\Omega \\ R_{IN} = 100k\Omega \\ R_{IN} = 1000k\Omega \end{array} \\ V_{IN} = 1000K\Omega \end{array} \\ V_{CC} = 15V, \ V_{EE} = 0V \\ V_{IN} = 15V \\ C_{L} = 1000F, \ R_{L} = 0.18\Omega \\ R_{IN} = 1000k\Omega \end{array} $
Sink Current with Varying Input Resistances	I _{SINK}	_	7.7 6.5 4.4 2.3 0.46	_	A	
Switching Times with Low Load Capacitance $C_L = 10nF$	t _{d(rise)} t _r t _{d(fall)} t _f	_	8 48 16 35	_	ns	$V_{CC} = 15V, V_{EE} = 0V$ $V_{IN} = 0 \text{ to } 15V$ $R_{IN} = 1k\Omega$ $C_L = 10nF, R_L = 0.18\Omega$
Switching Times with High Load Capacitance $C_L = 100nF$	t _{d(rise)} t _r t _{d(fall)} t _f	_	46 419 47 467	_	ns	$V_{CC} = 15V, V_{EE} = 0V$ $V_{IN} = 0 \text{ to } 15V$ $R_{IN} = 1k\Omega$ $C_L = 100nF, R_L = 0.18\Omega$
Switching Times with Asymmetric Source and Sink Resistors	t _{d(rise)} tr t _{d(fall)} t _f	_	27 208 11 53	_	ns	$\begin{split} &V_{CC} = 20V, V_{EE} = -18V \\ &V_{IN} = -18V to 20V \\ &R_{IN} = 1k\Omega \\ &C_L = 10nF, R_L = 0.18\Omega \\ &R_{SOURCE} = 4.7\Omega, R_{SINK} = 0\Omega \; (\text{See page 7}). \end{split}$

Switching Test Circuit and Timing Diagram



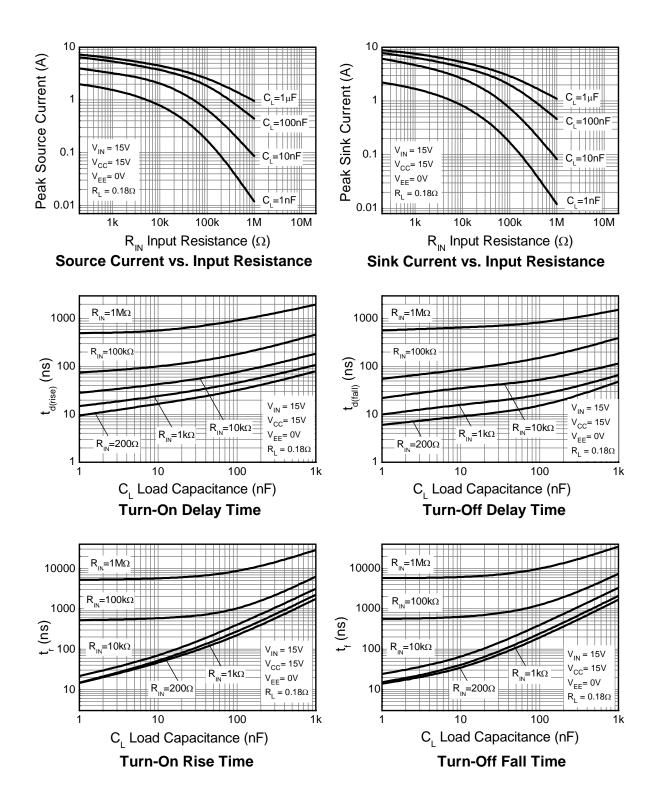


Typical Switching Characteristics (@T_A = +25°C, unless otherwise specified.)





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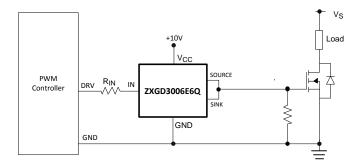




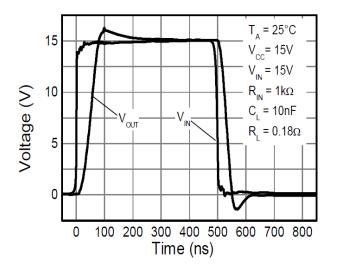
Circuit Examples

ZXGD3006E6Q Driving a MOSFET

Application example of the ZXGD3006E6Q driving the gate of a MOSFET from 0 to +15V.



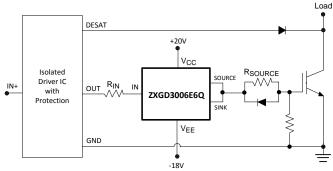
Switching Time Characteristic



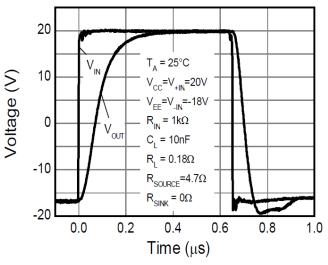
Symmetric Source and Sink Resistors

ZXGD3006E6Q Driving an IGBT

Application example of ZXGD3006E6Q driving the gate of an IGBT with independent t_{ON} and t_{OFF} using asymmetric R_{SOURCE} and R_{SINK} . In addition, the gate is driven negative to -18V to prevent dV/dt induced false triggering.



Switching Time Characteristic

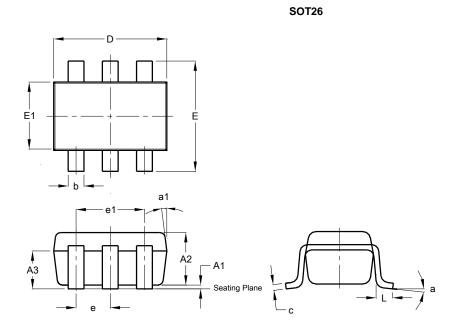


Asymmetric Source and Sink Resistors



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

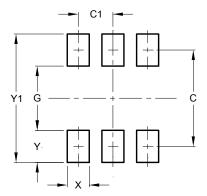


	SOT26						
Dim	Min	Max	Тур				
A1	0.013	0.10	0.05				
A2	1.00	1.30	1.10				
A3	0.70	0.80	0.75				
b	0.35	0.50	0.38				
С	0.10	0.20	0.15				
D	2.90	3.10	3.00				
е	-	-	0.95				
e1	-	-	1.90				
Е	2.70	3.00	2.80				
E1	1.50	1.70	1.60				
L	0.35	0.55	0.40				
а	-	-	8°				
a1	-	-	7°				
All	Dimen	sions	in mm				

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

SOT26



Dimensions	Value (in mm)
С	2.40
C1	0.95
G	1.60
Х	0.55
Y	0.80
Y1	3.20



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